

# MECHANICAL CASE OUTLINE

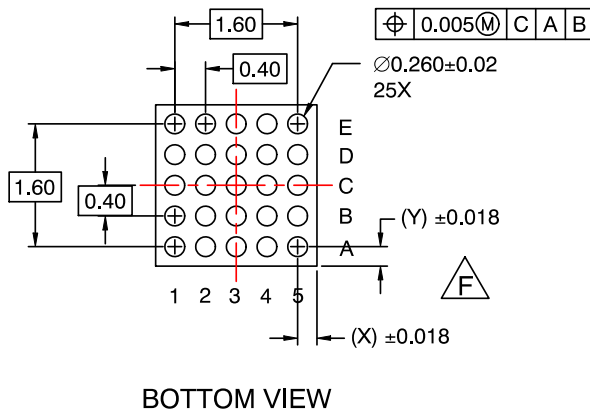
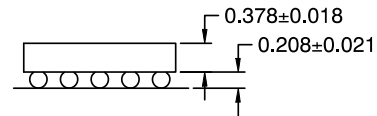
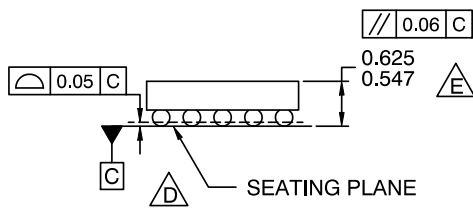
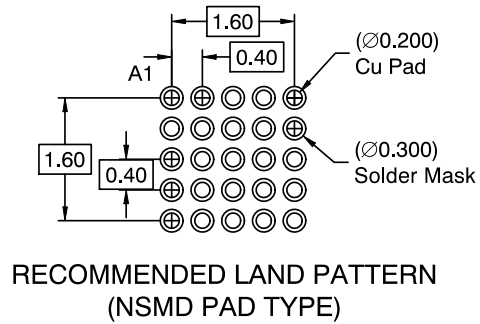
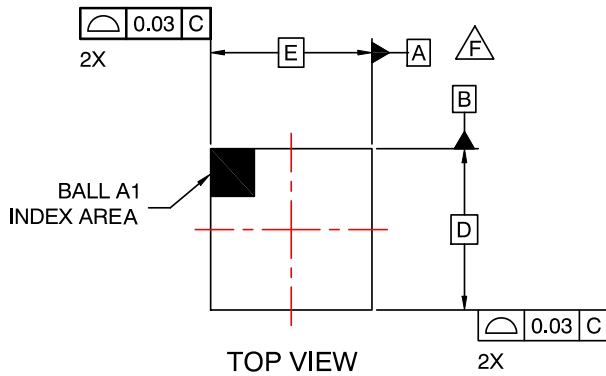
## PACKAGE DIMENSIONS

ON Semiconductor®



WLCSP25 2.05x2.05x0.586  
CASE 567SP  
ISSUE O

DATE 30 NOV 2016



### NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547–625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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